# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
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YU-XUAN HUANG	09/08/2020
KUO-JI CHEN	08/31/2020

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#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17181196

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NAME OF SUBMITTER:	PAUL V. KELLER
SIGNATURE:	/Paul V. Keller/
DATE SIGNED:	02/22/2021

**Total Attachments: 5** 

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TSMC Docket No. P20200508US00 Docket No. TSMCP1214US

# PATENT ASSIGNMENT

## PARTIES TO THE ASSIGNMENT

Assignor(s):
Tao Yi Hung

Assignor(s):
Yu-Xuan Huang

Assignor(s): Kuo-Ji Chen

Assignee:
Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

#### AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled "DUAL SUBSTRATE SIDE ESD DIODE FOR HIGH SPEED CIRCUIT" for which:

a non-provisional application for United States Letters Patent:

~	
$\boxtimes$	was executed on even date preparatory to filing (each inventor should sign this
	Assignment on the same day as he/she signs the Declaration); or
	was filed on and accorded U.S. Serial No; or
	I hereby authorize and request my attorney associated with Customer No
	107476, to insert on the designated lines below the filing date and application
	number of said application when known:
	U.S. Serial No.
	filad on

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to Page 1 of 5

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any letters patent that may be granted therefore in the United States and in any and all

foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of

which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto

ASSIGNEE its successors and assigns, the entire right, title and interest in and to said

invention and improvements, said application and any and all letters patent which may be

granted for said invention in the United States of America and its territorial possessions and

in any and all foreign countries, and in any and all divisions, reissues, re-examinations and

continuations thereof, including the right to file foreign applications directly in the name of

ASSIGNEE and to claim priority rights deriving from said United States application to which

said foreign applications are entitled by virtue of international convention, treaty or otherwise,

said invention, application and all letters patent on said invention to be held and enjoyed by

ASSIGNEE and its successors and assigns for their use and benefit and of their successors

and assigns as fully and entirely as the same would have been held and enjoyed by

ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S)

hereby authorize and request the Commissioner of Patents and Trademarks to issue all

letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all

instruments and documents required for the making and prosecution of applications for

United States and foreign letters patent on said invention, for litigation regarding said letters

patent, or for the purpose of protecting title to said invention or letters patent therefore.

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2°2° / 8/14 Date Name 1st Inventor Tao yi Hung

TSMC Docket No. P20200508US00 Docket No. TSMCP1214US

2020/9/8

Date

Name 2<sup>nd</sup> Inventor Yu-Xuan Huanc

TSMC Docket No. P20200508US00 Docket No. TSMCP1214US

2020/08/31. Date

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